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[Understanding Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details

Product Status	Active
Number of LABs/CLBs	6036
Number of Logic Elements/Cells	-
Total RAM Bits	-
Number of I/O	203
Number of Gates	108000
Voltage - Supply	2.25V ~ 5.25V
Mounting Type	Surface Mount
Operating Temperature	-55°C ~ 125°C (TJ)
Package / Case	256-BFCQFP with Tie Bar
Supplier Device Package	256-CQFP (75x75)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/a54sx72a-cq256b

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General Description

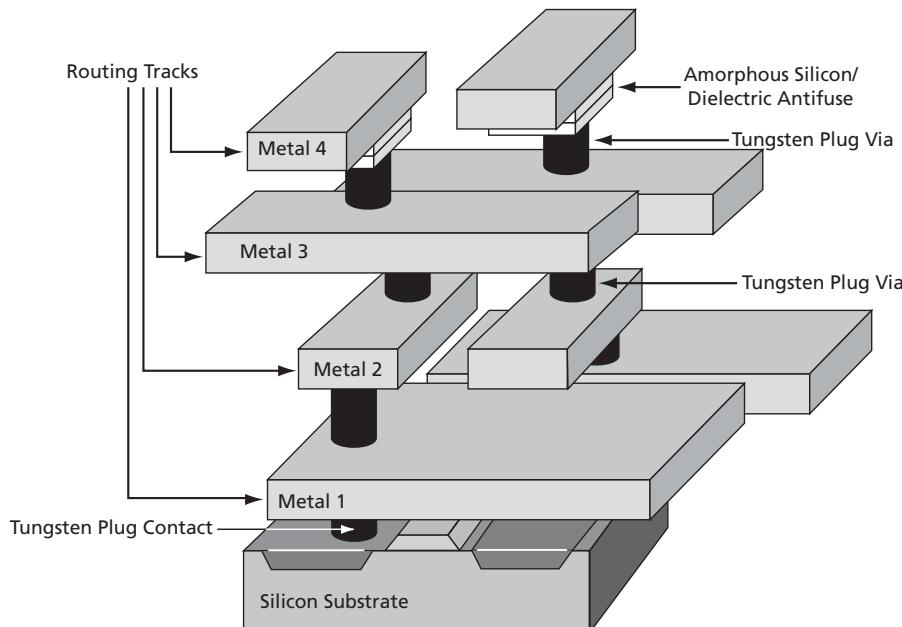
Introduction

The Actel SX-A family of FPGAs offers a cost-effective, single-chip solution for low-power, high-performance designs. Fabricated on $0.22\text{ }\mu\text{m} / 0.25\text{ }\mu\text{m}$ CMOS antifuse technology and with the support of 2.5 V, 3.3 V and 5 V I/Os, the SX-A is a versatile platform to integrate designs while significantly reducing time-to-market.

SX-A Family Architecture

The SX-A family's device architecture provides a unique approach to module organization and chip routing that satisfies performance requirements and delivers the most optimal register/logic mix for a wide variety of applications.

Interconnection between these logic modules is achieved using Actel's patented metal-to-metal programmable antifuses interconnect elements (Figure 1-1). The antifuses are normally open circuit and, when programmed, form a permanent low-impedance connection.



Note: The A54SX72A device has four layers of metal with the antifuse between Metal 3 and Metal 4. The A54SX08A, A54SX16A, and A54SX32A devices have three layers of metal with the antifuse between Metal 2 and Metal 3.

Figure 1-1 • SX-A Family Interconnect Elements

Routing Resources

The routing and interconnect resources of SX-A devices are in the top two metal layers above the logic modules (Figure 1-1 on page 1-1), providing optimal use of silicon, thus enabling the entire floor of the device to be spanned with an uninterrupted grid of logic modules. Interconnection between these logic modules is achieved using the Actel patented metal-to-metal programmable antifuse interconnect elements. The antifuses are normally open circuits and, when programmed, form a permanent low-impedance connection.

Clusters and SuperClusters can be connected through the use of two innovative local routing resources called FastConnect and DirectConnect, which enable extremely fast and predictable interconnection of modules within Clusters and SuperClusters (Figure 1-5 on page 1-4 and Figure 1-6 on page 1-4). This routing architecture also dramatically reduces the number of antifuses required to complete a circuit, ensuring the highest possible performance, which is often required in applications such as fast counters, state machines, and data path logic. The interconnect elements (i.e., the antifuses and metal tracks) have lower capacitance and lower resistance than any other device of similar capacity, leading to the fastest signal propagation in the industry.

DirectConnect is a horizontal routing resource that provides connections from a C-cell to its neighboring R-Cell in a given SuperCluster. DirectConnect uses a hardwired signal path requiring no programmable

interconnection to achieve its fast signal propagation time of less than 0.1 ns.

FastConnect enables horizontal routing between any two logic modules within a given SuperCluster, and vertical routing with the SuperCluster immediately below it. Only one programmable connection is used in a FastConnect path, delivering a maximum pin-to-pin propagation time of 0.3 ns.

In addition to DirectConnect and FastConnect, the architecture makes use of two globally oriented routing resources known as segmented routing and high-drive routing. The Actel segmented routing structure provides a variety of track lengths for extremely fast routing between SuperClusters. The exact combination of track lengths and antifuses within each path is chosen by the 100% automatic place-and-route software to minimize signal propagation delays.

The general system of routing tracks allows any logic module in the array to be connected to any other logic or I/O module. Within this system, most connections typically require three or fewer antifuses, resulting in fast and predictable performance.

The unique local and general routing structure featured in SX-A devices allows 100% pin-locking with full logic utilization, enables concurrent printed circuit board (PCB) development, reduces design time, and allows designers to achieve performance goals with minimum effort.

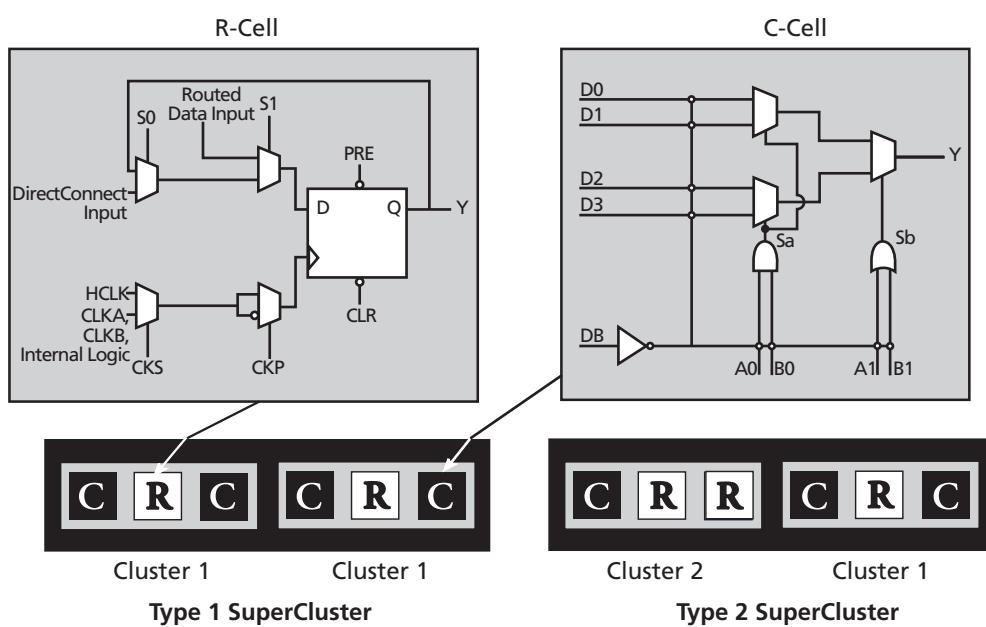


Figure 1-4 • Cluster Organization

JTAG Instructions

Table 1-7 lists the supported instructions with the corresponding IR codes for SX-A devices.

Table 1-8 lists the codes returned after executing the IDCODE instruction for SX-A devices. Note that bit 0 is always '1'. Bits 11-1 are always '02F', which is the Actel manufacturer code.

Table 1-7 • JTAG Instruction Code

Instructions (IR4:IR0)	Binary Code
EXTEST	00000
SAMPLE/PRELOAD	00001
INTEST	00010
USERCODE	00011
IDCODE	00100
HighZ	01110
CLAMP	01111
Diagnostic	10000
BYPASS	11111
Reserved	All others

Table 1-8 • JTAG Instruction Code

Device	Process	Revision	Bits 31-28	Bits 27-12
A54SX08A	0.22 μ	0	8, 9	40B4, 42B4
		1	A, B	40B4, 42B4
A54SX16A	0.22 μ	0	9	40B8, 42B8
		1	B	40B8, 42B8
	0.25 μ	1	B	22B8
A54SX32A	0.2 2 μ	0	9	40BD, 42BD
		1	B	40BD, 42BD
	0.25 μ	1	B	22BD
A54SX72A	0.22 μ	0	9	40B2, 42B2
		1	B	40B2, 42B2
	0.25 μ	1	B	22B2

Probing Capabilities

SX-A devices also provide an internal probing capability that is accessed with the JTAG pins. The Silicon Explorer II diagnostic hardware is used to control the TDI, TCK, TMS, and TDO pins to select the desired nets for debugging. The user assigns the selected internal nets in Actel Silicon Explorer II software to the PRA/PRB output pins for observation. Silicon Explorer II automatically places the device into JTAG mode. However, probing functionality is only activated when the TRST pin is driven high or left floating, allowing the internal pull-up resistor to pull TRST High. If the TRST pin is held Low, the TAP controller remains in the Test-Logic-Reset state so no probing can be performed. However, the user must drive the TRST pin High or allow the internal pull-up resistor to pull TRST High.

When selecting the **Reserve Probe Pin** box as shown in [Figure 1-12 on page 1-9](#), direct the layout tool to reserve the PRA and PRB pins as dedicated outputs for probing. This **Reserve** option is merely a guideline. If the designer assigns user I/Os to the PRA and PRB pins and selects the **Reserve Probe Pin** option, Designer Layout will override the **Reserve Probe Pin** option and place the user I/Os on those pins.

To allow probing capabilities, the security fuse must not be programmed. Programming the security fuse disables the JTAG and probe circuitry. [Table 1-9](#) summarizes the possible device configurations for probing once the device leaves the Test-Logic-Reset JTAG state.

Table 1-9 • Device Configuration Options for Probe Capability (TRST Pin Reserved)

JTAG Mode	TRST ¹	Security Fuse Programmed	PRA, PRB ²	TDI, TCK, TDO ²
Dedicated	Low	No	User I/O ³	JTAG Disabled
	High	No	Probe Circuit Outputs	JTAG I/O
Flexible	Low	No	User I/O ³	User I/O ³
	High	No	Probe Circuit Outputs	JTAG I/O
		Yes	Probe Circuit Secured	Probe Circuit Secured

Notes:

1. If the TRST pin is not reserved, the device behaves according to TRST = High as described in the table.
2. Avoid using the TDI, TCK, TDO, PRA, and PRB pins as input or bidirectional ports. Since these pins are active during probing, input signals will not pass through these pins and may cause contention.
3. If no user signal is assigned to these pins, they will behave as unused I/Os in this mode. Unused pins are automatically tristated by the Designer software.

Table 2-19 • A54SX08A Timing Characteristics
 (Worst-Case Commercial Conditions $V_{CCA} = 2.25\text{ V}$, $V_{CCI} = 3.0\text{ V}$, $T_J = 70^\circ\text{C}$)

Parameter	Description	-2 Speed		-1 Speed		Std. Speed	-F Speed	Units
		Min.	Max.	Min.	Max.	Min.	Max.	
3.3 V PCI Output Module Timing¹								
t_{DLH}	Data-to-Pad Low to High	2.2	2.4	2.9	4.0	ns		
t_{DHL}	Data-to-Pad High to Low	2.3	2.6	3.1	4.3	ns		
t_{ENZL}	Enable-to-Pad, Z to L	1.7	1.9	2.2	3.1	ns		
t_{ENZH}	Enable-to-Pad, Z to H	2.2	2.4	2.9	4.0	ns		
t_{ENLZ}	Enable-to-Pad, L to Z	2.8	3.2	3.8	5.3	ns		
t_{ENHZ}	Enable-to-Pad, H to Z	2.3	2.6	3.1	4.3	ns		
d_{TLH}^2	Delta Low to High	0.03	0.03	0.04	0.045	ns/pF		
d_{THL}^2	Delta High to Low	0.015	0.015	0.015	0.025	ns/pF		
3.3 V LVTTL Output Module Timing³								
t_{DLH}	Data-to-Pad Low to High	3.0	3.4	4.0	5.6	ns		
t_{DHL}	Data-to-Pad High to Low	3.0	3.3	3.9	5.5	ns		
t_{DHLS}	Data-to-Pad High to Low—low slew	10.4	11.8	13.8	19.3	ns		
t_{ENZL}	Enable-to-Pad, Z to L	2.6	2.9	3.4	4.8	ns		
t_{ENZLS}	Enable-to-Pad, Z to L—low slew	18.9	21.3	25.4	34.9	ns		
t_{ENZH}	Enable-to-Pad, Z to H	3	3.4	4	5.6	ns		
t_{ENLZ}	Enable-to-Pad, L to Z	3.3	3.7	4.4	6.2	ns		
t_{ENHZ}	Enable-to-Pad, H to Z	3	3.3	3.9	5.5	ns		
d_{TLH}^2	Delta Low to High	0.03	0.03	0.04	0.045	ns/pF		
d_{THL}^2	Delta High to Low	0.015	0.015	0.015	0.025	ns/pF		
d_{THLS}^2	Delta High to Low—low slew	0.053	0.067	0.073	0.107	ns/pF		

Notes:

1. Delays based on 10 pF loading and 25 Ω resistance.
2. To obtain the slew rate, substitute the appropriate Delta value, load capacitance, and the V_{CCI} value into the following equation:

$$\text{Slew Rate [V/ns]} = (0.1 * V_{CCI} - 0.9 * V_{CCI}) / (C_{load} * d_{T[|LH|HL|HLS]})$$
where C_{load} is the load capacitance driven by the I/O in pF
 $d_{T[|LH|HL|HLS]}$ is the worst case delta value from the datasheet in ns/pF.
3. Delays based on 35 pF loading.

Table 2-24 • A54SX16A Timing Characteristics
 (Worst-Case Commercial Conditions $V_{CCA} = 2.25\text{ V}$, $V_{CCI} = 4.75\text{ V}$, $T_J = 70^\circ\text{C}$)

Parameter	Description	-3 Speed*	-2 Speed	-1 Speed	Std. Speed	-F Speed	Units
		Min.	Max.	Min.	Max.	Min.	
Dedicated (Hardwired) Array Clock Networks							
t_{HCKH}	Input Low to High (Pad to R-cell Input)	1.2	1.4	1.6	1.8	2.8	ns
t_{HCKL}	Input High to Low (Pad to R-cell Input)	1.0	1.1	1.2	1.5	2.2	ns
t_{HPWH}	Minimum Pulse Width High	1.4	1.7	1.9	2.2	3.0	ns
t_{HPWL}	Minimum Pulse Width Low	1.4	1.7	1.9	2.2	3.0	ns
t_{HCKSW}	Maximum Skew	0.3	0.3	0.4	0.4	0.7	ns
t_{HP}	Minimum Period	2.8	3.4	3.8	4.4	6.0	ns
f_{HMAX}	Maximum Frequency	357	294	263	227	167	MHz
Routed Array Clock Networks							
t_{RCKH}	Input Low to High (Light Load) (Pad to R-cell Input)	1.0	1.2	1.3	1.6	2.2	ns
t_{RCKL}	Input High to Low (Light Load) (Pad to R-cell Input)	1.1	1.3	1.5	1.7	2.4	ns
t_{RCKH}	Input Low to High (50% Load) (Pad to R-cell Input)	1.1	1.3	1.5	1.7	2.4	ns
t_{RCKL}	Input High to Low (50% Load) (Pad to R-cell Input)	1.1	1.3	1.5	1.7	2.4	ns
t_{RCKH}	Input Low to High (100% Load) (Pad to R-cell Input)	1.3	1.5	1.7	2.0	2.8	ns
t_{RCKL}	Input High to Low (100% Load) (Pad to R-cell Input)	1.3	1.5	1.7	2.0	2.8	ns
t_{RPWH}	Minimum Pulse Width High	1.4	1.7	1.9	2.2	3.0	ns
t_{RPWL}	Minimum Pulse Width Low	1.4	1.7	1.9	2.2	3.0	ns
t_{RCKSW}	Maximum Skew (Light Load)	0.8	0.9	1.0	1.2	1.7	ns
t_{RCKSW}	Maximum Skew (50% Load)	0.8	0.9	1.0	1.2	1.7	ns
t_{RCKSW}	Maximum Skew (100% Load)	1.0	1.1	1.3	1.5	2.1	ns

Note: *All -3 speed grades have been discontinued.

Table 2-26 • A54SX16A Timing Characteristics
 (Worst-Case Commercial Conditions $V_{CCA} = 2.25\text{ V}$, $V_{CCI} = 3.0\text{ V}$, $T_J = 70^\circ\text{C}$)

Parameter	Description	-3 Speed¹	-2 Speed	-1 Speed	Std. Speed	-F Speed	Units
		Min.	Max.	Min.	Max.	Min.	
3.3 V PCI Output Module Timing²							
t_{DLH}	Data-to-Pad Low to High	2.0	2.3	2.6	3.1	4.3	ns
t_{DHL}	Data-to-Pad High to Low	2.2	2.5	2.8	3.3	4.6	ns
t_{ENZL}	Enable-to-Pad, Z to L	1.4	1.7	1.9	2.2	3.1	ns
t_{ENZH}	Enable-to-Pad, Z to H	2.0	2.3	2.6	3.1	4.3	ns
t_{ENLZ}	Enable-to-Pad, L to Z	2.5	2.8	3.2	3.8	5.3	ns
t_{ENHZ}	Enable-to-Pad, H to Z	2.2	2.5	2.8	3.3	4.6	ns
d_{TLH}^3	Delta Low to High	0.025	0.03	0.03	0.04	0.045	ns/pF
d_{THL}^3	Delta High to Low	0.015	0.015	0.015	0.015	0.025	ns/pF
3.3 V LVTTL Output Module Timing⁴							
t_{DLH}	Data-to-Pad Low to High	2.8	3.2	3.6	4.3	6.0	ns
t_{DHL}	Data-to-Pad High to Low	2.7	3.1	3.5	4.1	5.7	ns
t_{DHLS}	Data-to-Pad High to Low—low slew	9.5	10.9	12.4	14.6	20.4	ns
t_{ENZL}	Enable-to-Pad, Z to L	2.2	2.6	2.9	3.4	4.8	ns
t_{ENZLS}	Enable-to-Pad, Z to L—low slew	15.8	18.9	21.3	25.4	34.9	ns
t_{ENZH}	Enable-to-Pad, Z to H	2.8	3.2	3.6	4.3	6.0	ns
t_{ENLZ}	Enable-to-Pad, L to Z	2.9	3.3	3.7	4.4	6.2	ns
t_{ENHZ}	Enable-to-Pad, H to Z	2.7	3.1	3.5	4.1	5.7	ns
d_{TLH}^3	Delta Low to High	0.025	0.03	0.03	0.04	0.045	ns/pF
d_{THL}^3	Delta High to Low	0.015	0.015	0.015	0.015	0.025	ns/pF
d_{THLS}^3	Delta High to Low—low slew	0.053	0.053	0.067	0.073	0.107	ns/pF

Notes:

1. All -3 speed grades have been discontinued.
2. Delays based on 10 pF loading and 25 Ω resistance.
3. To obtain the slew rate, substitute the appropriate Delta value, load capacitance, and the V_{CCI} value into the following equation:

$$\text{Slew Rate [V/ns]} = (0.1 * V_{CCI} - 0.9 * V_{CCI}) / (C_{load} * d_{T[LH|HL|HLS]})$$

where C_{load} is the load capacitance driven by the I/O in pF.
 $d_{T[LH|HL|HLS]}$ is the worst case delta value from the datasheet in ns/pF.
4. Delays based on 35 pF loading.

Table 2-36 • A54SX72A Timing Characteristics (Continued)
 (Worst-Case Commercial Conditions $V_{CCA} = 2.25\text{ V}$, $V_{CCI} = 2.25\text{ V}$, $T_J = 70^\circ\text{C}$)

Parameter	Description	-3 Speed*	-2 Speed	-1 Speed	Std. Speed	-F Speed	Units
		Min.	Max.	Min.	Max.	Min.	
t_{QCKH}	Input Low to High (100% Load) (Pad to R-cell Input)	3.0	3.4	3.9	4.6	6.4	ns
t_{QCHKL}	Input High to Low (100% Load) (Pad to R-cell Input)	2.9	3.4	3.8	4.5	6.3	ns
t_{QPWH}	Minimum Pulse Width High	1.5	1.7	2.0	2.3	3.2	ns
t_{QPWL}	Minimum Pulse Width Low	1.5	1.7	2.0	2.3	3.2	ns
t_{QCKSW}	Maximum Skew (Light Load)	0.2	0.3	0.3	0.3	0.5	ns
t_{QCKSW}	Maximum Skew (50% Load)	0.4	0.5	0.5	0.6	0.9	ns
t_{QCKSW}	Maximum Skew (100% Load)	0.4	0.5	0.5	0.6	0.9	ns

Note: *All -3 speed grades have been discontinued.

208-Pin PQFP				
Pin Number	A54SX08A Function	A54SX16A Function	A54SX32A Function	A54SX72A Function
1	GND	GND	GND	GND
2	TDI, I/O	TDI, I/O	TDI, I/O	TDI, I/O
3	I/O	I/O	I/O	I/O
4	NC	I/O	I/O	I/O
5	I/O	I/O	I/O	I/O
6	NC	I/O	I/O	I/O
7	I/O	I/O	I/O	I/O
8	I/O	I/O	I/O	I/O
9	I/O	I/O	I/O	I/O
10	I/O	I/O	I/O	I/O
11	TMS	TMS	TMS	TMS
12	V _{CCI}	V _{CCI}	V _{CCI}	V _{CCI}
13	I/O	I/O	I/O	I/O
14	NC	I/O	I/O	I/O
15	I/O	I/O	I/O	I/O
16	I/O	I/O	I/O	I/O
17	NC	I/O	I/O	I/O
18	I/O	I/O	I/O	GND
19	I/O	I/O	I/O	V _{CCA}
20	NC	I/O	I/O	I/O
21	I/O	I/O	I/O	I/O
22	I/O	I/O	I/O	I/O
23	NC	I/O	I/O	I/O
24	I/O	I/O	I/O	I/O
25	NC	NC	NC	I/O
26	GND	GND	GND	GND
27	V _{CCA}	V _{CCA}	V _{CCA}	V _{CCA}
28	GND	GND	GND	GND
29	I/O	I/O	I/O	I/O
30	TRST, I/O	TRST, I/O	TRST, I/O	TRST, I/O
31	NC	I/O	I/O	I/O
32	I/O	I/O	I/O	I/O
33	I/O	I/O	I/O	I/O
34	I/O	I/O	I/O	I/O
35	NC	I/O	I/O	I/O

208-Pin PQFP				
Pin Number	A54SX08A Function	A54SX16A Function	A54SX32A Function	A54SX72A Function
36	I/O	I/O	I/O	I/O
37	I/O	I/O	I/O	I/O
38	I/O	I/O	I/O	I/O
39	NC	I/O	I/O	I/O
40	V _{CCI}	V _{CCI}	V _{CCI}	V _{CCI}
41	V _{CCA}	V _{CCA}	V _{CCA}	V _{CCA}
42	I/O	I/O	I/O	I/O
43	I/O	I/O	I/O	I/O
44	I/O	I/O	I/O	I/O
45	I/O	I/O	I/O	I/O
46	I/O	I/O	I/O	I/O
47	I/O	I/O	I/O	I/O
48	NC	I/O	I/O	I/O
49	I/O	I/O	I/O	I/O
50	NC	I/O	I/O	I/O
51	I/O	I/O	I/O	I/O
52	GND	GND	GND	GND
53	I/O	I/O	I/O	I/O
54	I/O	I/O	I/O	I/O
55	I/O	I/O	I/O	I/O
56	I/O	I/O	I/O	I/O
57	I/O	I/O	I/O	I/O
58	I/O	I/O	I/O	I/O
59	I/O	I/O	I/O	I/O
60	V _{CCI}	V _{CCI}	V _{CCI}	V _{CCI}
61	NC	I/O	I/O	I/O
62	I/O	I/O	I/O	I/O
63	I/O	I/O	I/O	I/O
64	NC	I/O	I/O	I/O
65	I/O	I/O	NC	I/O
66	I/O	I/O	I/O	I/O
67	NC	I/O	I/O	I/O
68	I/O	I/O	I/O	I/O
69	I/O	I/O	I/O	I/O
70	NC	I/O	I/O	I/O

100-TQFP			
Pin Number	A54SX08A Function	A54SX16A Function	A54SX32A Function
71	I/O	I/O	I/O
72	I/O	I/O	I/O
73	I/O	I/O	I/O
74	I/O	I/O	I/O
75	I/O	I/O	I/O
76	I/O	I/O	I/O
77	I/O	I/O	I/O
78	I/O	I/O	I/O
79	I/O	I/O	I/O
80	I/O	I/O	I/O
81	I/O	I/O	I/O
82	V _{CCI}	V _{CCI}	V _{CCI}
83	I/O	I/O	I/O
84	I/O	I/O	I/O
85	I/O	I/O	I/O
86	I/O	I/O	I/O
87	CLKA	CLKA	CLKA
88	CLKB	CLKB	CLKB
89	NC	NC	NC
90	V _{CCA}	V _{CCA}	V _{CCA}
91	GND	GND	GND
92	PRA, I/O	PRA, I/O	PRA, I/O
93	I/O	I/O	I/O
94	I/O	I/O	I/O
95	I/O	I/O	I/O
96	I/O	I/O	I/O
97	I/O	I/O	I/O
98	I/O	I/O	I/O
99	I/O	I/O	I/O
100	TCK, I/O	TCK, I/O	TCK, I/O

329-Pin PBGA	
Pin Number	A54SX32A Function
V22	I/O
V23	I/O
W1	I/O
W2	I/O
W3	I/O
W4	I/O
W20	I/O
W21	I/O
W22	I/O
W23	NC
Y1	NC
Y2	I/O
Y3	I/O
Y4	GND
Y5	I/O
Y6	I/O
Y7	I/O
Y8	I/O
Y9	I/O
Y10	I/O
Y11	I/O
Y12	V _{CCA}
Y13	NC
Y14	I/O
Y15	I/O
Y16	I/O
Y17	I/O
Y18	I/O
Y19	I/O
Y20	GND
Y21	I/O
Y22	I/O
Y23	I/O

256-Pin FBGA

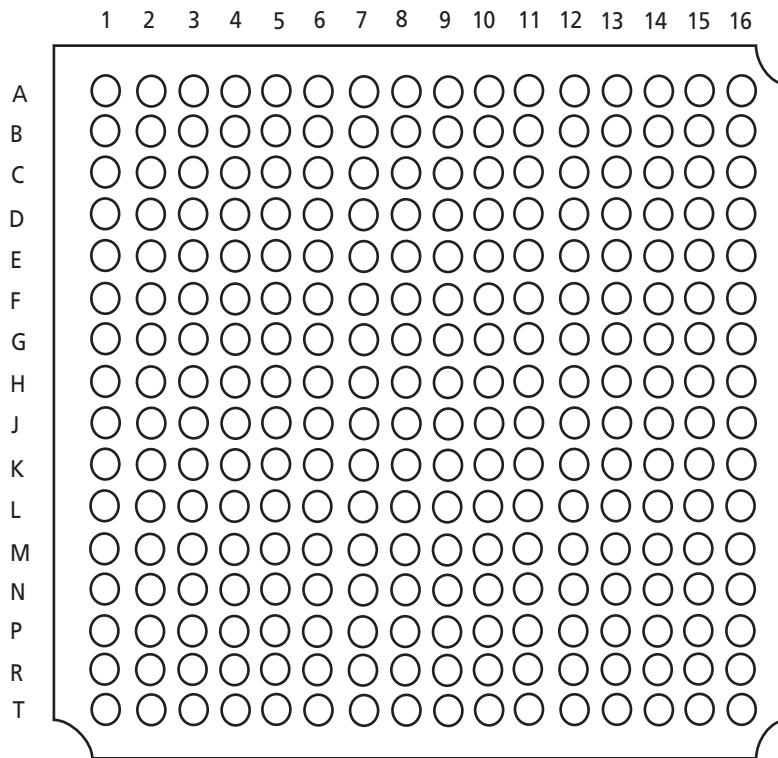


Figure 3-7 • 256-Pin FBGA (Top View)

Note

For Package Manufacturing and Environmental information, visit Resource center at
<http://www.actel.com/products/rescenter/package/index.html>.

256-Pin FBGA			
Pin Number	A54SX16A Function	A54SX32A Function	A54SX72A Function
E11	I/O	I/O	I/O
E12	I/O	I/O	I/O
E13	NC	I/O	I/O
E14	I/O	I/O	I/O
E15	I/O	I/O	I/O
E16	I/O	I/O	I/O
F1	I/O	I/O	I/O
F2	I/O	I/O	I/O
F3	I/O	I/O	I/O
F4	TMS	TMS	TMS
F5	I/O	I/O	I/O
F6	I/O	I/O	I/O
F7	V _{CCI}	V _{CCI}	V _{CCI}
F8	V _{CCI}	V _{CCI}	V _{CCI}
F9	V _{CCI}	V _{CCI}	V _{CCI}
F10	V _{CCI}	V _{CCI}	V _{CCI}
F11	I/O	I/O	I/O
F12	VCCA	VCCA	VCCA
F13	I/O	I/O	I/O
F14	I/O	I/O	I/O
F15	I/O	I/O	I/O
F16	I/O	I/O	I/O
G1	NC	I/O	I/O
G2	I/O	I/O	I/O
G3	NC	I/O	I/O
G4	I/O	I/O	I/O
G5	I/O	I/O	I/O
G6	V _{CCI}	V _{CCI}	V _{CCI}
G7	GND	GND	GND
G8	GND	GND	GND
G9	GND	GND	GND
G10	GND	GND	GND
G11	V _{CCI}	V _{CCI}	V _{CCI}
G12	I/O	I/O	I/O
G13	GND	GND	GND
G14	NC	I/O	I/O
G15	V _{CCA}	V _{CCA}	V _{CCA}

256-Pin FBGA			
Pin Number	A54SX16A Function	A54SX32A Function	A54SX72A Function
G16	I/O	I/O	I/O
H1	I/O	I/O	I/O
H2	I/O	I/O	I/O
H3	V _{CCA}	V _{CCA}	V _{CCA}
H4	TRST, I/O	TRST, I/O	TRST, I/O
H5	I/O	I/O	I/O
H6	V _{CCI}	V _{CCI}	V _{CCI}
H7	GND	GND	GND
H8	GND	GND	GND
H9	GND	GND	GND
H10	GND	GND	GND
H11	V _{CCI}	V _{CCI}	V _{CCI}
H12	I/O	I/O	I/O
H13	I/O	I/O	I/O
H14	I/O	I/O	I/O
H15	I/O	I/O	I/O
H16	NC	I/O	I/O
J1	NC	I/O	I/O
J2	NC	I/O	I/O
J3	NC	I/O	I/O
J4	I/O	I/O	I/O
J5	I/O	I/O	I/O
J6	V _{CCI}	V _{CCI}	V _{CCI}
J7	GND	GND	GND
J8	GND	GND	GND
J9	GND	GND	GND
J10	GND	GND	GND
J11	V _{CCI}	V _{CCI}	V _{CCI}
J12	I/O	I/O	I/O
J13	I/O	I/O	I/O
J14	I/O	I/O	I/O
J15	I/O	I/O	I/O
J16	I/O	I/O	I/O
K1	I/O	I/O	I/O
K2	I/O	I/O	I/O
K3	NC	I/O	I/O
K4	V _{CCA}	V _{CCA}	V _{CCA}

256-Pin FBGA			
Pin Number	A54SX16A Function	A54SX32A Function	A54SX72A Function
P15	I/O	I/O	I/O
P16	I/O	I/O	I/O
R1	I/O	I/O	I/O
R2	GND	GND	GND
R3	I/O	I/O	I/O
R4	NC	I/O	I/O
R5	I/O	I/O	I/O
R6	I/O	I/O	I/O
R7	I/O	I/O	I/O
R8	I/O	I/O	I/O
R9	HCLK	HCLK	HCLK
R10	I/O	I/O	QCLKB
R11	I/O	I/O	I/O
R12	I/O	I/O	I/O
R13	I/O	I/O	I/O
R14	I/O	I/O	I/O
R15	GND	GND	GND
R16	GND	GND	GND
T1	GND	GND	GND
T2	I/O	I/O	I/O
T3	I/O	I/O	I/O
T4	NC	I/O	I/O
T5	I/O	I/O	I/O
T6	I/O	I/O	I/O
T7	I/O	I/O	I/O
T8	I/O	I/O	I/O
T9	V _{CCA}	V _{CCA}	V _{CCA}
T10	I/O	I/O	I/O
T11	I/O	I/O	I/O
T12	NC	I/O	I/O
T13	I/O	I/O	I/O
T14	I/O	I/O	I/O
T15	TDO, I/O	TDO, I/O	TDO, I/O
T16	GND	GND	GND

484-Pin FBGA

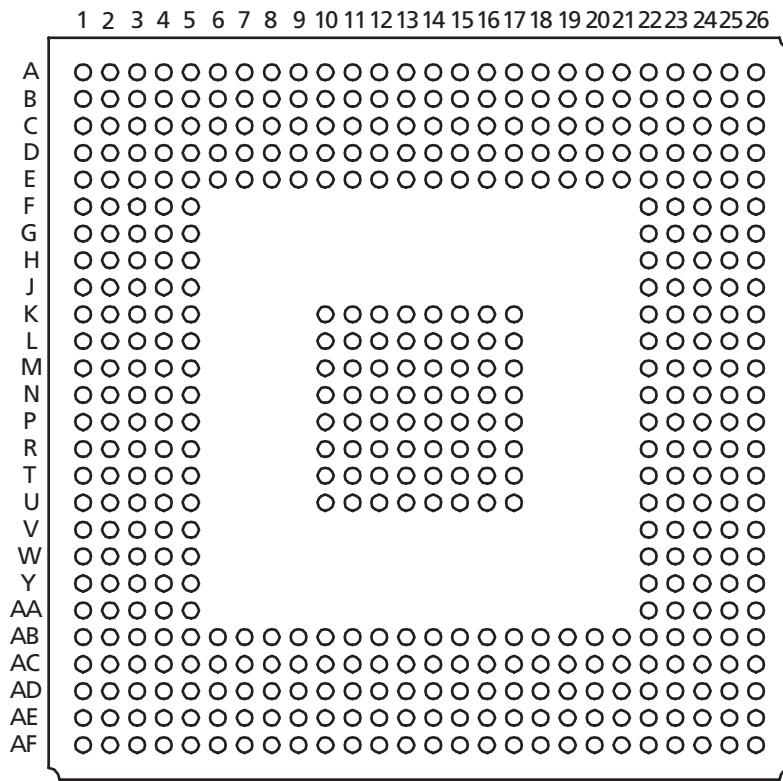


Figure 3-8 • 484-Pin FBGA (Top View)

Note

For Package Manufacturing and Environmental information, visit Resource center at <http://www.actel.com/products/rescenter/package/index.html>.

484-Pin FBGA		
Pin Number	A54SX32A Function	A54SX72A Function
A1	NC*	NC
A2	NC*	NC
A3	NC*	I/O
A4	NC*	I/O
A5	NC*	I/O
A6	I/O	I/O
A7	I/O	I/O
A8	I/O	I/O
A9	I/O	I/O
A10	I/O	I/O
A11	NC*	I/O
A12	NC*	I/O
A13	I/O	I/O
A14	NC*	NC
A15	NC*	I/O
A16	NC*	I/O
A17	I/O	I/O
A18	I/O	I/O
A19	I/O	I/O
A20	I/O	I/O
A21	NC*	I/O
A22	NC*	I/O
A23	NC*	I/O
A24	NC*	I/O
A25	NC*	NC
A26	NC*	NC
AA1	NC*	I/O
AA2	NC*	I/O
AA3	V _{CCA}	V _{CCA}
AA4	I/O	I/O
AA5	I/O	I/O
AA22	I/O	I/O
AA23	I/O	I/O
AA24	I/O	I/O
AA25	NC*	I/O

484-Pin FBGA		
Pin Number	A54SX32A Function	A54SX72A Function
AA26	NC*	I/O
AB1	NC*	NC
AB2	V _{CCI}	V _{CCI}
AB3	I/O	I/O
AB4	I/O	I/O
AB5	NC*	I/O
AB6	I/O	I/O
AB7	I/O	I/O
AB8	I/O	I/O
AB9	I/O	I/O
AB10	I/O	I/O
AB11	I/O	I/O
AB12	PRB, I/O	PRB, I/O
AB13	V _{CCA}	V _{CCA}
AB14	I/O	I/O
AB15	I/O	I/O
AB16	I/O	I/O
AB17	I/O	I/O
AB18	I/O	I/O
AB19	I/O	I/O
AB20	TDO, I/O	TDO, I/O
AB21	GND	GND
AB22	NC*	I/O
AB23	I/O	I/O
AB24	I/O	I/O
AB25	NC*	I/O
AB26	NC*	I/O
AC1	I/O	I/O
AC2	I/O	I/O
AC3	I/O	I/O
AC4	NC*	I/O
AC5	V _{CCI}	V _{CCI}
AC6	I/O	I/O
AC7	V _{CCI}	V _{CCI}
AC8	I/O	I/O

484-Pin FBGA		
Pin Number	A54SX32A Function	A54SX72A Function
AC9	I/O	I/O
AC10	I/O	I/O
AC11	I/O	I/O
AC12	I/O	QCLKA
AC13	I/O	I/O
AC14	I/O	I/O
AC15	I/O	I/O
AC16	I/O	I/O
AC17	I/O	I/O
AC18	I/O	I/O
AC19	I/O	I/O
AC20	V _{CCI}	V _{CCI}
AC21	I/O	I/O
AC22	I/O	I/O
AC23	NC*	I/O
AC24	I/O	I/O
AC25	NC*	I/O
AC26	NC*	I/O
AD1	I/O	I/O
AD2	I/O	I/O
AD3	GND	GND
AD4	I/O	I/O
AD5	I/O	I/O
AD6	I/O	I/O
AD7	I/O	I/O
AD8	I/O	I/O
AD9	V _{CCI}	V _{CCI}
AD10	I/O	I/O
AD11	I/O	I/O
AD12	I/O	I/O
AD13	V _{CCI}	V _{CCI}
AD14	I/O	I/O
AD15	I/O	I/O
AD16	I/O	I/O
AD17	V _{CCI}	V _{CCI}

Note: *These pins must be left floating on the A54SX32A device.

484-Pin FBGA		
Pin Number	A54SX32A Function	A54SX72A Function
AD18	I/O	I/O
AD19	I/O	I/O
AD20	I/O	I/O
AD21	I/O	I/O
AD22	I/O	I/O
AD23	V _{CCI}	V _{CCI}
AD24	NC*	I/O
AD25	NC*	I/O
AD26	NC*	I/O
AE1	NC*	NC
AE2	I/O	I/O
AE3	NC*	I/O
AE4	NC*	I/O
AE5	NC*	I/O
AE6	NC*	I/O
AE7	I/O	I/O
AE8	I/O	I/O
AE9	I/O	I/O
AE10	I/O	I/O
AE11	NC*	I/O
AE12	I/O	I/O
AE13	I/O	I/O
AE14	I/O	I/O
AE15	NC*	I/O
AE16	NC*	I/O
AE17	I/O	I/O
AE18	I/O	I/O
AE19	I/O	I/O
AE20	I/O	I/O
AE21	NC*	I/O
AE22	NC*	I/O
AE23	NC*	I/O
AE24	NC*	I/O
AE25	NC*	NC
AE26	NC*	NC

484-Pin FBGA		
Pin Number	A54SX32A Function	A54SX72A Function
AF1	NC*	NC
AF2	NC*	NC
AF3	NC	I/O
AF4	NC*	I/O
AF5	NC*	I/O
AF6	NC*	I/O
AF7	I/O	I/O
AF8	I/O	I/O
AF9	I/O	I/O
AF10	I/O	I/O
AF11	NC*	I/O
AF12	NC*	NC
AF13	HCLK	HCLK
AF14	I/O	QCLKB
AF15	NC*	I/O
AF16	NC*	I/O
AF17	I/O	I/O
AF18	I/O	I/O
AF19	I/O	I/O
AF20	NC*	I/O
AF21	NC*	I/O
AF22	NC*	I/O
AF23	NC*	I/O
AF24	NC*	I/O
AF25	NC*	NC
AF26	NC*	NC
B1	NC*	NC
B2	NC*	NC
B3	NC*	I/O
B4	NC*	I/O
B5	NC*	I/O
B6	I/O	I/O
B7	I/O	I/O
B8	I/O	I/O
B9	I/O	I/O

484-Pin FBGA		
Pin Number	A54SX32A Function	A54SX72A Function
B10	I/O	I/O
B11	NC*	I/O
B12	NC*	I/O
B13	V _{CCI}	V _{CCI}
B14	CLKA	CLKA
B15	NC*	I/O
B16	NC*	I/O
B17	I/O	I/O
B18	V _{CCI}	V _{CCI}
B19	I/O	I/O
B20	I/O	I/O
B21	NC*	I/O
B22	NC*	I/O
B23	NC*	I/O
B24	NC*	I/O
B25	I/O	I/O
B26	NC*	NC
C1	NC*	I/O
C2	NC*	I/O
C3	NC*	I/O
C4	NC*	I/O
C5	I/O	I/O
C6	V _{CCI}	V _{CCI}
C7	I/O	I/O
C8	I/O	I/O
C9	V _{CCI}	V _{CCI}
C10	I/O	I/O
C11	I/O	I/O
C12	I/O	I/O
C13	PRA, I/O	PRA, I/O
C14	I/O	I/O
C15	I/O	QCLKD
C16	I/O	I/O
C17	I/O	I/O
C18	I/O	I/O

Note: *These pins must be left floating on the A54SX32A device.

Previous Version	Changes in Current Version (v5.3)	Page
v4.0 (continued)	Table 2-12 was updated.	2-11
	The was updated.	2-14
	The "Sample Path Calculations" were updated.	2-14
	Table 2-13 was updated.	2-17
	Table 2-13 was updated.	2-17
	All timing tables were updated.	2-18 to 2-52
v3.0	The "Actel Secure Programming Technology with FuseLock™ Prevents Reverse Engineering and Design Theft" section was updated.	1-i
	The "Ordering Information" section was updated.	1-ii
	The "Temperature Grade Offering" section was updated.	1-iii
	The Figure 1-1 • SX-A Family Interconnect Elements was updated.	1-1
	The "Clock Resources" section was updated	1-5
	The Table 1-1 • SX-A Clock Resources is new.	1-5
	The "User Security" section is new.	1-7
	The "I/O Modules" section was updated.	1-7
	The Table 1-2 • I/O Features was updated.	1-8
	The Table 1-3 • I/O Characteristics for All I/O Configurations is new.	1-8
	The Table 1-4 • Power-Up Time at which I/Os Become Active is new	1-8
	The Figure 1-12 • Device Selection Wizard is new.	1-9
	The "Boundary-Scan Pin Configurations and Functions" section is new.	1-9
	The Table 1-9 • Device Configuration Options for Probe Capability (TRST Pin Reserved) is new.	1-11
	The "SX-A Probe Circuit Control Pins" section was updated.	1-12
	The "Design Considerations" section was updated.	1-12
	The Figure 1-13 • Probe Setup was updated.	1-12
	The Design Environment was updated.	1-13
	The Figure 1-13 • Design Flow is new.	1-11
	The "Absolute Maximum Ratings*" section was updated.	1-12
	The "Recommended Operating Conditions" section was updated.	1-12
	The "Electrical Specifications" section was updated.	1-12
	The "2.5V LVCMS2 Electrical Specifications" section was updated.	1-13
	The "SX-A Timing Model" and "Sample Path Calculations" equations were updated.	1-23
	The "Pin Description" section was updated.	1-15
v2.0.1	The "Design Environment" section has been updated.	1-13
	The "I/O Modules" section, and Table 1-2 • I/O Features have been updated.	1-8
	The "SX-A Timing Model" section and the "Timing Characteristics" section have new timing numbers.	1-23